

## LOA0015LA Terrain Database DO-200B Release Statement

Terrain Database Version: 633  
Date of Release: April 12, 2023  
Letter of Acceptance Status: Current

Honeywell complies with the objectives of Advisory Circular 20-153B and DO-200B by utilizing the alternative means of compliance using AC 20-153A and DO-200A regarding the processing of Terrain, Obstacle, Runway and Magnetic Variation data. For this Type 2 Letter of Acceptance (LOA), compatibility has been established with the systems identified in the Honeywell International Inc. LOA Parts Number Matrix EGPWS Database document, 993-0109-001 Rev.N dated March 15, 2023. There are no deviations to the agreed upon Data Quality Requirements (DQR's).

Runway and Obstacle data is based on AIRAC cycle 2302 data received from Jeppesen and Lufthansa Systems. The Obstacle data is supplemented with data from the FAA Digital Obstacle version 230122 (FAA data is not published per AIRAC cycles). Honeywell source data supplier, Jeppesen, has received a Type 1 Letter of Acceptance from the FAA for the ARINC 424 Runway data provided to Honeywell. Honeywell source data supplier, Lufthansa Systems, has received a Type 1 Letter of Acceptance from EASA for the Obstacle data provided to Honeywell.

Data alteration has not been performed on source data from Type 1 LOA suppliers or authoritative sources. In some cases, Honeywell has originated and independently validated new data based on other reliable information and selected this data as an alternative source.

All other sources used to produce Terrain databases are from non-authoritative sources or suppliers who have not received a Type 1 Letter of Acceptance. Honeywell has performed independent validation of this data. Information regarding the changes implemented in this release are provided on the below websites, located under 'Change Info'.

ASDS: <https://ads.honeywell.com>

INDS: <https://inds.epicinds.com>

Wingman Services: <https://wingmanservices.bendixking.com>



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